

## Ideal junction properties:-

- For a metal-semiconductor junction ( $\phi_m > \phi_s$ ) i.e. (rectifying contact), we will find the expression for depletion region width ( $w$ ), E-field and space-charge.
- We will assume "full depletion approximation".

↳ It is obtained by assuming that the semiconductor is fully depleted over distance  $x_n$ , called the "depletion region".

- As the semiconductor is depleted of mobile carriers within the depletion region, the charge density in that region is due to the ionized donors.

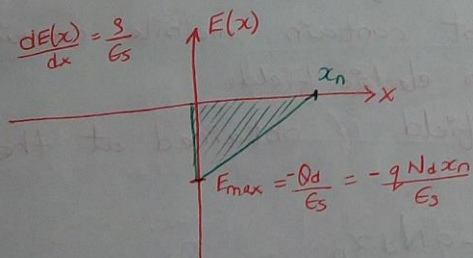
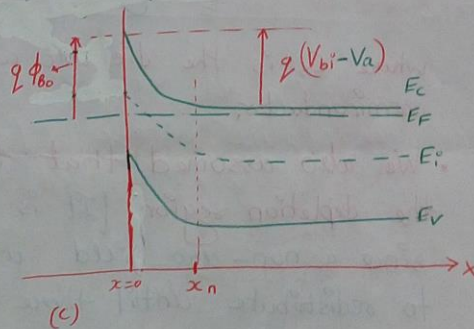
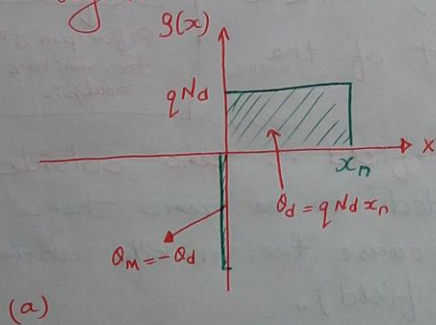


fig: (a) Charge density vs  $x$   
 (b) Electric field vs  $x$   
 (c) EBD as obtained with full depletion analysis  
 (For Metal-Semiconductor J<sup>n</sup>)  
 ( $\phi_m > \phi_s$ ) (n-type)

- Outside the depletion region, the semiconductor is assumed neutral. This gives the following expressions for the charge density  $\rho(x)$ :

$$\rho(x) = qN_d \quad ; \quad 0 < x < x_n \quad \left\{ \text{Fig a} \right\}$$

$$= 0 \quad ; \quad x_n < x$$

The charge in the n-type Semiconductor is exactly balanced by the charge in the metal,  $Q_M$ , so that no E-field exists except around the Metal-semiconductor interface.

Now, using Gauss's law, we obtain electric field as a function of position (fig b)

$$E(x) = -\frac{qN_d}{\epsilon_s} (x_n - x) \quad ; \quad 0 < x < x_n$$

$$= 0 \quad ; \quad x_n \leq x$$

where  $\epsilon_s$  is the dielectric constant of the semiconductor.

Analysis

It is similar to a p-n one-side  $J^0$ , where p-region is heavily doped.

Refer p-n  $J^0$  for similar analysis

- We also assumed that the E-field is zero outside the depletion region. (It is expected to be zero there since a non-zero field would cause the mobile carriers to redistribute until there is no field).
- The depletion region does not contain mobile carriers so that there can be an electric field.
- The largest value of E-field is obtained at the M-S interface as,

$$E_{\max}(x=0) = -\frac{qN_d x_n}{\epsilon_s} = -\frac{Q_d}{\epsilon_s}$$

$$|E_{\max}| = \frac{qN_d x_n}{\epsilon_s}$$

Here " $x_n$  or  $W$ " or  $x_d$  means same.

• Following the similar analysis (as p-n J<sup>n</sup>), we can next find potential  $\phi(x)$  & then find depletion layer width.

• Expression for depletion layer width ' $x_n$ ' or ' $W$ ' is

$$x_d = x_n = W = \sqrt{\frac{2 \epsilon_s (V_{bi} - 0)}{q N_d}} \quad \text{--- At equilibrium}$$

$$W = \sqrt{\frac{2 \epsilon_s (V_{bi} - V_a)}{q N_d}} \quad \text{--- with applied bias } V_a$$

→ Junction capacitance:

In addition, we can obtain the capacitance as a function of the applied voltage by taking the derivative of the charge  $Q_d$  w.r.t applied bias ' $V_a$ '.

$$C_J = \left| \frac{dQ_d}{dV_a} \right| \quad ; \quad Q_d = -q N_d x_n = -q N_d W$$

Solving, we get

$$C_J = \sqrt{\frac{q \epsilon_s N_d}{2(V_{bi} - V_a)}} = \frac{\epsilon_s}{W} \quad \text{--- (1)}$$

• The last term in the (1), indicates that the expression of a parallel plate capacitor still applies.  
 $\left( \frac{C}{A} = \frac{\epsilon}{d} \right)$

Extra:-

One can understand this once one realizes that the charge added/removed from the depletion layer as one  $\downarrow$ ses/ $\uparrow$ ses the applied  $v_{tg}$  is added/removed only at the edge of the depletion region.

## → Ideal Junction properties: "same"

(Derivation for space charge region width and junction capacitance for a metal-n type semiconductor for contacts)

- The ideal metal-semiconductor junction discussed so far has striking similarities with the pn junction.
- The electric field in the space-charge region is determined using the Poisson's equation, given by

$$\frac{dE}{dx} = \frac{\rho(x)}{\epsilon_s} \quad \text{--- (1)}$$

where  $\rho(x)$  is the space-charge volume density  
 $\epsilon_s$  is the permittivity of the semiconductor.

- Assuming a uniformly doped semiconductor, then by integrating eq<sup>n</sup> (1), we get  $(\rho(x) \approx qN_d)$  "n-type SC"

$$E = \int \frac{qN_d}{\epsilon_s} dx = \frac{qN_dx}{\epsilon_s} + C_1 \quad \text{--- (2)}$$

where,  $C_1$  is a constant of integration.

(Refer fig 1.b),

An important difference w.r.t pn junction appear at this stage. → A metal cannot sustain an electric field in its bulk and, therefore, E-field is zero inside the metal.

Suppose at  $x=x_0$  (where <sup>"same"</sup>  $x_0$  represents the point 12 where the E-field is zero at the space-charge region edge in the semiconductor.

Then using eq<sup>n</sup> (2), we have

$$E=0 = \frac{qNd x_0}{\epsilon_s} + C_1$$

This leads to,

$$C_1 = -\frac{qNd x_0}{\epsilon_s} \quad \text{--- (3)}$$

Using (3) & (4), we have

$$E = -\frac{qNd}{\epsilon_s} (x_0 - x) \quad \text{--- (4)}$$

Thus, the electric field is a linear function of distance and has its maximum value at the metal-semiconductor interface.

Since the E-field is zero inside the metal, a negative surface charge must exist in the metal at the Metal-semiconductor junction.

The space-charge width 'W' can be expressed as

$$W = x_0 = \left[ \frac{2 \epsilon_s (V_{bi} + V_R)}{qNd} \right]^{1/2} \quad \text{--- (5)}$$

(Expression similar to one-sided p-n junction)

where,  $V_R$  represents the applied reverse-bias. 13

• Similarly, the junction capacitance (per unit area),  $C_J^0$  is given by,

$$C_J^0 = q N_d \frac{dx_n}{dV_R} \quad \text{--- (6)}$$

$$\text{ie } C_J^0 = \left[ \frac{q \epsilon_s N_d}{2(V_{bi} + V_R)} \right]^{1/2} \quad \text{--- (7)}$$

• Evaluating  $(1/C_J^0)^2$  from eq<sup>n</sup> (7) results in

$$\frac{1}{C_J^0{}^2} = \frac{2(V_{bi} + V_R)}{q \epsilon_s N_d} \quad \text{--- (8)}$$

• Thus, the slope of the curve obtained using eq<sup>n</sup> (8) yields semiconductor doping ' $N_d$ '. The curve can also be used to obtain  $V_{bi}$ .

• The magnitude of  $V_{bi}$  can then yield the Schottky barrier  $\phi_{B0}$ , i.e.

$$qV_{bi} = q(\phi_{B0} - \phi_n) \quad \text{--- (9)}$$

• The value of  $\phi_n$  is the difference bet<sup>n</sup>  $E_F$  and  $E_C$  of the semiconductor.

$$\phi_n = \frac{kT}{q} \ln\left(\frac{N_C}{N_d}\right)$$

1. A metal-semiconductor contact is formed between gold (Au) and n-type Si doped to a level  $N_d = 5 \times 10^{16} \text{ cm}^{-3}$  at 300K. Calculate the ideal Schottky barrier height, built-in potential barrier, space-charge width at zero bias, and maximum electric field for zero bias. Assume the work function of gold to be 5.1 eV,  $\chi_s = 4.01 \text{ eV}$  and the effective density of states function  $N_c = 2.8 \times 10^{19} / \text{cm}^3$ .

Sol<sup>n</sup>: a) Ideal barrier height  $\phi_{B0}$  is

$$\phi_{B0} = \phi_m - \chi_s = 5.1 - 4.01 = \underline{1.09 \text{ eV}}$$

Also,  $\phi_n = \frac{kT}{q} \ln \left[ \frac{N_c}{N_d} \right]$  ;  $\frac{kT}{q} \approx 0.0259 \text{ V}$

ie  $\phi_n = 0.0259 \ln \left[ \frac{2.8 \times 10^{19}}{5 \times 10^{16}} \right] \approx \frac{0.165 \text{ V}}{q}$  ( $\phi_n \approx 0.165 \text{ eV}$ )

b) Built-in potential barrier,  $V_{bi}$  is

$$V_{bi} = \frac{\phi_{B0} - \phi_n}{q}$$

ie  $V_{bi} = \frac{(1.09 - 0.165) \text{ eV}}{q} = \underline{0.925 \text{ V}}$

c) Space-charge width  $x_n$  at zero bias is,

$$x_n = \left[ \frac{2 \epsilon_s V_{bi}}{q N_d} \right]^{1/2}$$

$$= \left[ \frac{2 \times 11.7 \times 8.854 \times 10^{-14} \times 0.925}{1.6 \times 10^{-19} \times 5 \times 10^{16}} \right]^{1/2}$$

$$x_n = \underline{0.155 \times 10^{-4} \text{ cm}}$$

• The maximum electric field  $|E_{max}|$  at zero bias is, 15

$$|E_{max}| = \frac{q N_d x_n}{\epsilon_s}$$

$$= \frac{1.6 \times 10^{-19} \times 5 \times 10^{16} \times 0.155 \times 10^{-4}}{11.7 \times 8.85 \times 10^{-14}}$$

$$|E_{max}| = \underline{11.98 \times 10^4 \text{ V/cm}}$$

2. Consider a contact between tungsten and n-type Si doped to  $N_d = 10^{16} \text{ cm}^{-3}$  at  $T = 300 \text{ K}$ . Find the Schottky barrier height, built-in potential barrier, and maximum E-field for zero applied bias.

Given: Metal work function for tungsten is  $\phi_m = 4.55 \text{ V}$  and  $\chi = 4.01$ .  $N_c = 2.8 \times 10^{19} / \text{cm}^3$

Solution: a) Barrier height ( $\phi_{B0}$ ) is

$$\phi_{B0} = \phi_m - \chi = 4.55 - 4.01 = \underline{0.54 \text{ V}}$$

$$b) \phi_n = \frac{kT}{q} \ln \left[ \frac{N_c}{N_d} \right]$$

$$\phi_n = 0.0259 \ln \left[ \frac{2.8 \times 10^{19}}{10^{16}} \right] = \underline{0.206 \text{ V}}$$

$$\cdot V_{bi} = \phi_{B0} - \phi_n = 0.54 - 0.206 = \underline{0.33 \text{ V}}$$

c) Space-charge width at zero bias,

$$x_n = \left[ \frac{2 \epsilon_s V_{bi}}{q N_d} \right]^{1/2} = \frac{2 \times 11.7 \times 8.85 \times 10^{-14} \times 0.33}{1.6 \times 10^{-19} \times 10^{16}}$$

$$x_n = \underline{0.207 \times 10^{-4} \text{ cm}}$$



d) Maximum E-field is

16

$$|E_{\max}| = \frac{q N_d x_n}{\epsilon_s}$$

$$= \frac{1.6 \times 10^{-19} \times 10^{16} \times 0.207 \times 10^{-4}}{11.7 \times 8.85 \times 10^{-14}}$$

$$|E_{\max}| = \underline{3.2 \times 10^4 \text{ V/cm}}$$

3. Consider an ideal chromium to n-type silicon Schottky diode at  $T = 300\text{K}$ . Assume the semiconductor is doped with  $N_d = 3 \times 10^{15} \text{ cm}^{-3}$ .

Determine a) ideal Schottky barrier height

b) Peak electric field with an applied reverse bias voltage of 5V.

c) Junction capacitance or Depletion layer capacitance per unit area for a reverse bias voltage of 5V.

(Given: Work function for chromium  $\phi_m = 4.5 \text{ eV}$ , electron affinity for Si  $\chi = 4.01 \text{ eV}$ )

Solution:

a) Schottky barrier height ( $\phi_{Bo}$ ) is

$$\phi_{Bo} = \phi_m - \chi = (4.5 - 4.01) \text{ eV} = 0.49 \text{ eV}$$

$$b) |E_{\max}| = \frac{q N_d x_n}{\epsilon_s}$$

$$\text{where, } x_n = \left[ \frac{2 \epsilon_s (V_{bi} + V_R)}{q N_d} \right]^{1/2}$$

- Assuming the built-in potential barrier ' $V_{bi}$ ' to be very small as compared to applied R.B of 5V and hence ignoring it, we get

$$x_n = \left[ \frac{2 \epsilon_s (V_{bi} + V_R)}{q N_d} \right]^{1/2}, \text{ Neglecting } V_{bi}$$

$$x_n = \left[ \frac{2 \times 11.7 \times 8.854 \times 10^{-14} \times 5}{1.6 \times 10^{-19} \times 3 \times 10^{15}} \right]^{1/2}$$

$$x_n = 1.469 \times 10^{-4} \text{ cm}$$

$$\therefore E_{max} = \frac{q N_d x_n}{\epsilon_s}$$

$$= \frac{1.6 \times 10^{-19} \times 3 \times 10^{15} \times 1.469 \times 10^{-4}}{11.7 \times 8.85 \times 10^{-14}}$$

$$\approx 6.807 \times 10^4 \text{ V/cm}$$

c) Junction Capacitance ' $C_j$ '

$$C_j = \left[ \frac{q \epsilon_s N_d}{2(V_{bi} + V_R)} \right]^{1/2}, \text{ Neglecting } V_{bi}$$

$$= \left[ \frac{1.6 \times 10^{-19} \times 11.7 \times 8.854 \times 10^{-14} \times 3 \times 10^{15}}{2(5)} \right]^{1/2}$$

$$\approx 6.928 \times 10^{-9} \text{ F/cm}^2$$